

# P-Ch 30V Fast Switching MOSFETs

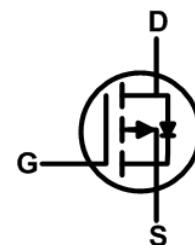
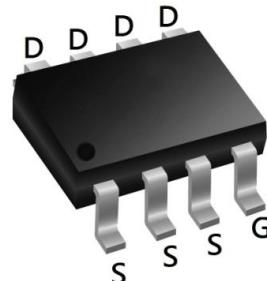
## RC25P03S

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

BVDSS	RDS(ON)	ID
-30V	5.8 mΩ	-25A

### SOP8 Pin Configuration



### General Description

The RC25P03S is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The RC25P03S meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	$V_{DS}$	-30	V
Gate-Source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current  $T_A=25^\circ\text{C}$	$I_D$	-25	A
$T_A=100^\circ\text{C}$		-8.8	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-60	A
Single Pulse Avalanche Energy <sup>2</sup>	EAS	80	mJ
Total Power Dissipation	$P_D$	3	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	41.6	$^\circ\text{C}/\text{W}$

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**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	$\mu\text{A}$
$T_J=100^\circ\text{C}$			-	-	-100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-	-2.5	V
Drain-Source On-Resistance <sup>4</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -12\text{A}$	-	5.8	9.2	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -10\text{A}$	-	8	14	
Forward Transconductance <sup>4</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = -10\text{V}, I_D = -10\text{A}$	-	50	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	3100	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	430	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	358	-	
Gate Resistance	$R_g$	$f = 1\text{MHz}$	-	9.5	-	$\Omega$
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}} = -10\text{V}, V_{\text{DS}} = -15\text{V}$ $I_D = -12\text{A}$	-	35	-	$\text{nC}$
Gate-Source Charge	$Q_{gs}$		-	9.9	-	
Gate-Drain Charge	$Q_{gd}$		-	10.5	-	
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}} = -10\text{V}, V_{\text{DD}} = -15\text{V}$ $R_G = 3\Omega, I_D = -12\text{A}$	-	10.8	-	$\text{ns}$
Rise Time	$t_r$		-	13.2	-	
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	73	-	
Fall Time	$t_f$		-	35	-	
Reverse Recovery Time	$t_{rr}$	$I_F = -12\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	-	25	-	$\text{ns}$
Reverse Recovery Charge	$Q_{rr}$		-	10	-	$\text{nC}$
<b>Drain-source body diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	$V_{\text{SD}}$	$I_S = -1\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	$T_A=25^\circ\text{C}$	$I_S$	-	-	-14	A

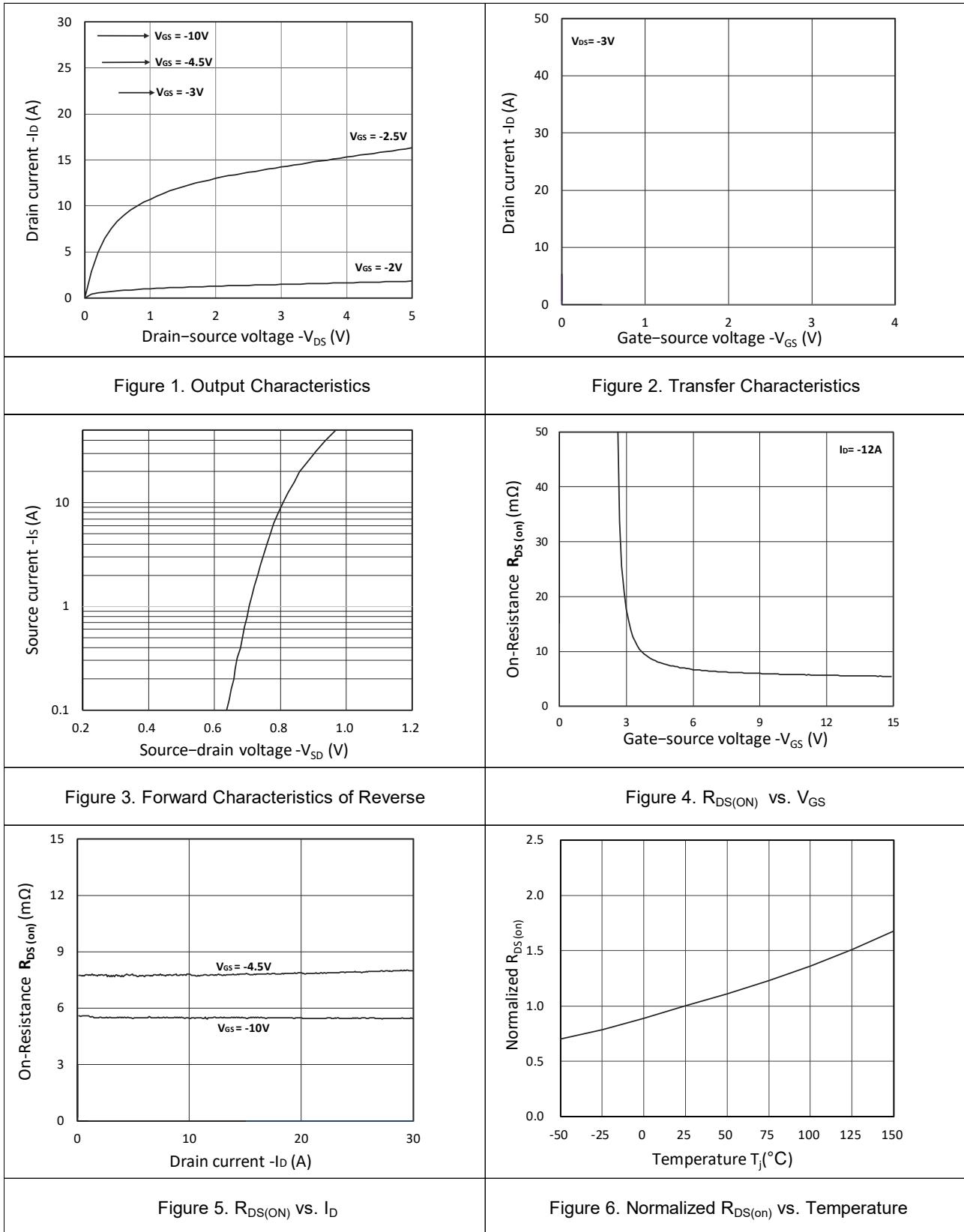
Notes:

- Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}= -25\text{V}, V_{\text{GS}}= -10\text{V}, L=0.1\text{mH}, I_{\text{AS}}= -40\text{A}$ .
- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
- This value is guaranteed by design hence it is not included in the production test.

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## RC25P03S

### Typical Characteristics



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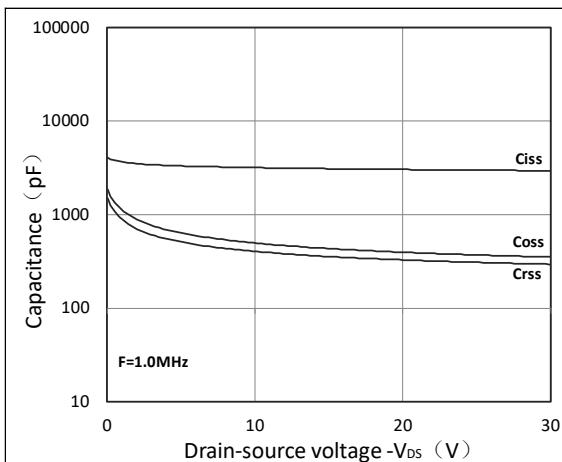


Figure 7. Capacitance Characteristics

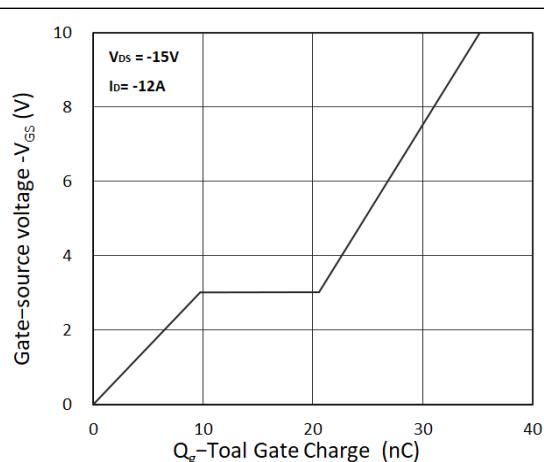


Figure 8. Gate Charge Characteristics

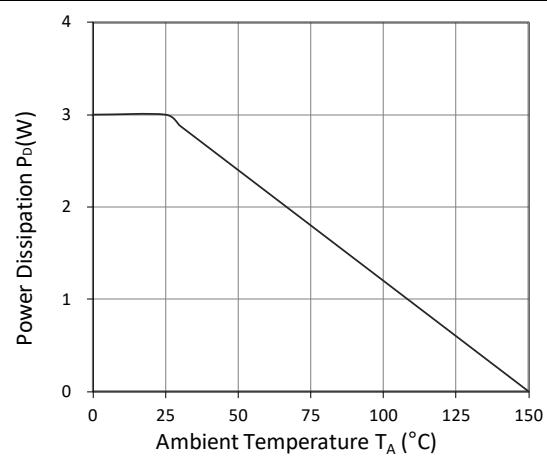


Figure 9. Power Dissipation

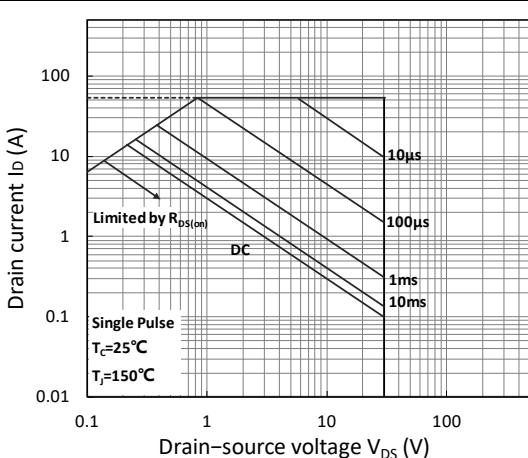


Figure 10. Safe Operating Area

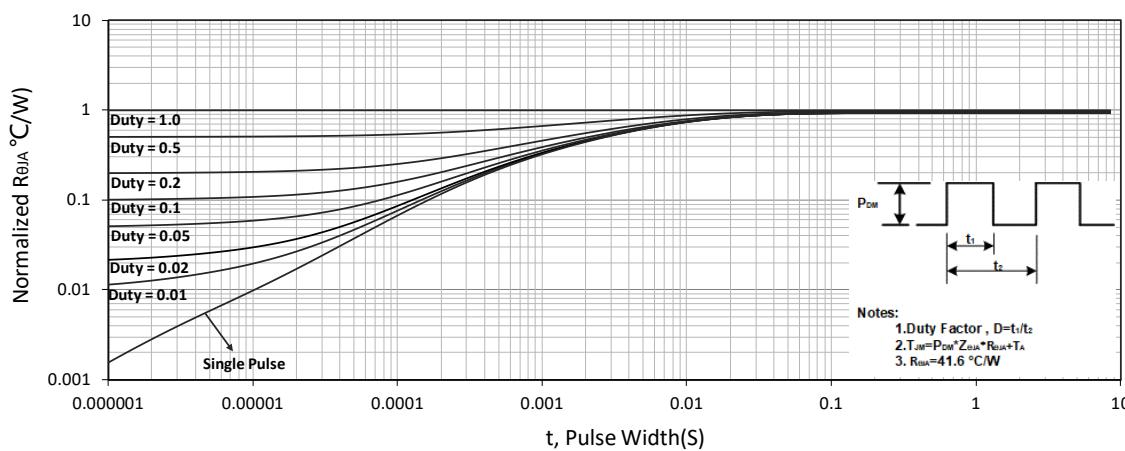


Figure 11. Normalized Maximum Transient Thermal Impedance

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### Test Circuit

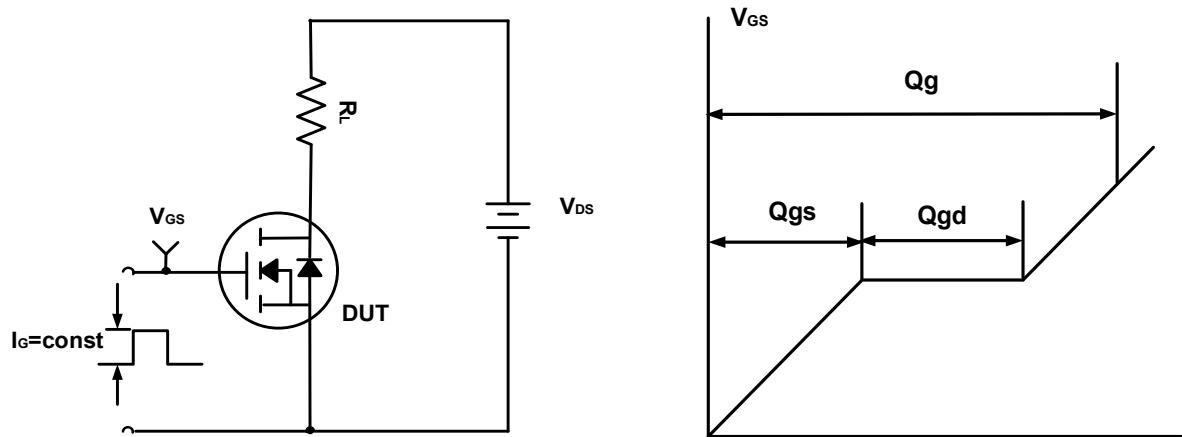


Figure A. Gate Charge Test Circuit & Waveforms

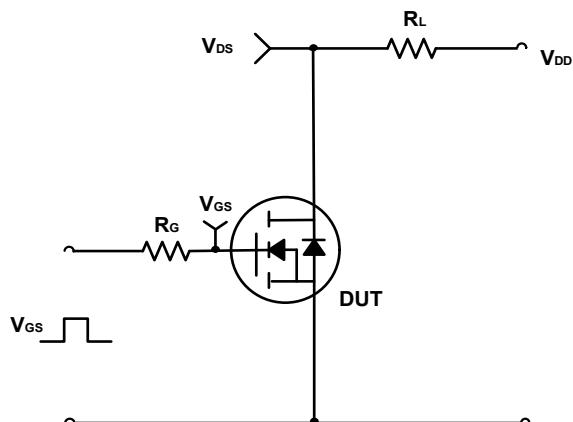


Figure B. Switching Test Circuit & Waveforms

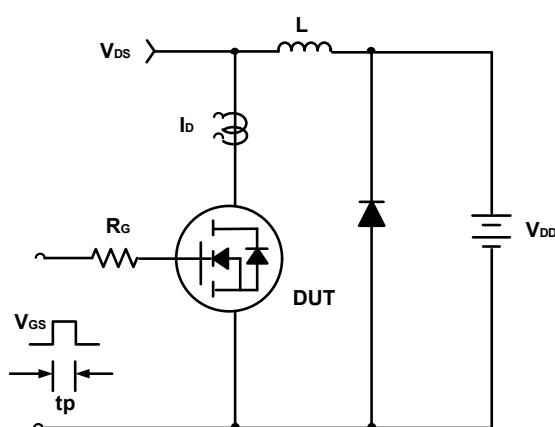
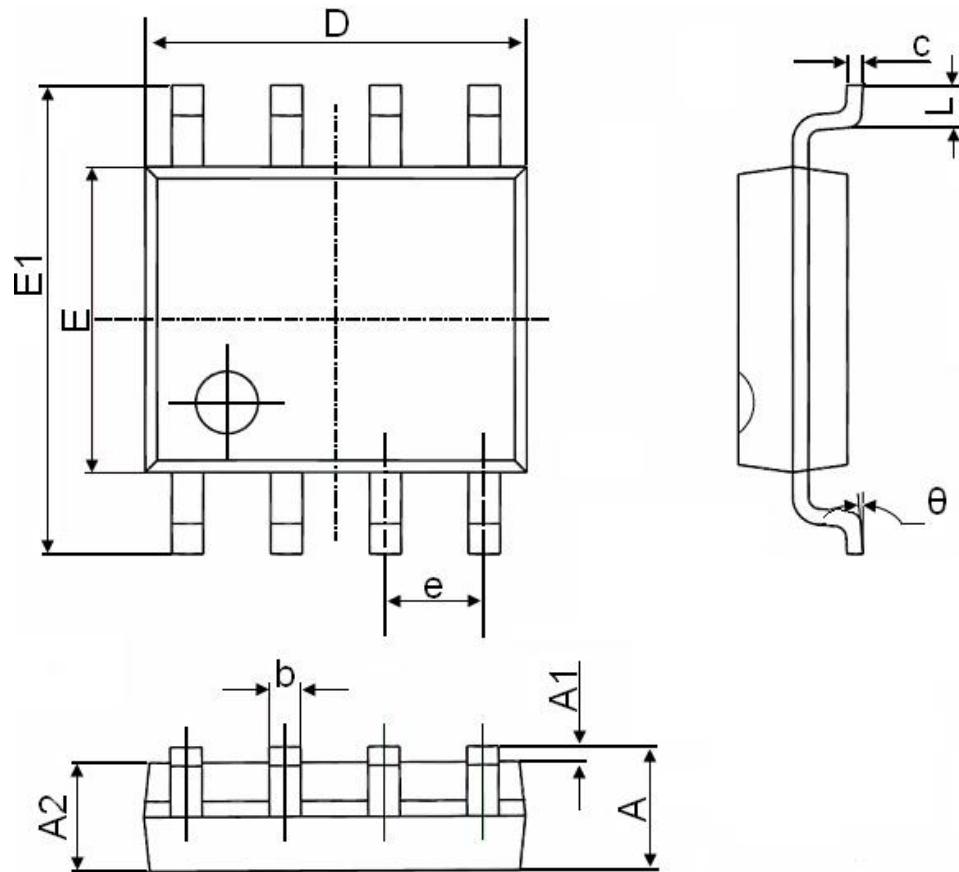


Figure C. Unclamped Inductive Switching Circuit & Waveforms

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### SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°